

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional)

1109.005

Application Number

Applicant(s)

Eichelberger et al.

Filing Date

Herewith

Group Art Unit

JC625 U.S. PTO
09/502078



U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
MDP	AA	5,841,193	11/24/98	Eichelberger et al.	257	723	#2

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

MDP	AB	"EPIC CSP Assembly and Reliability Methods," James E. Kohl et al., originally published in the Proceedings of CS198, Santa Clara, California, May 1998.
MDP	AC	"Low Cost Chip Scale Packaging and Interconnect Technology," James E. Kohl, et al., originally published in the Proceedings of the Surface Mount International Conference, San Jose, California, September 1997.

EXAMINER

Marcel A. Rigaud-Beaupre

DATE CONSIDERED

6/8/2001

EXAMINER Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.